

53927-**19	53927-5019
MODEL No.	MATERIAL No.

REVISED EC NO: J2014-0889 DRW: NESATO 2013/11/21 CHKD: ASHIMOTSU 2013/11/21 APPR: NUKITA 2013/11/21 REV A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY T. UENO		DATE 2004/05/17		TITLE CFA CARD CONN. 50P HEADER ASSY -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO		DATE 2004/05/17		molex SD-53927-001			
	30 OVER	±0.3	APPROVED BY M. SASAO		DATE 2004/05/17					
ANGULAR ±3 °		MATERIAL NO. SEE TABLE		DOCUMENT NO. SEE TABLE		SHEET NO. 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3								

NOTES

1. 材質

MATERIAL

ハウジング：ガラス入りLCP UL94V-0  
 HOUSING: LCP G.F. UL94V-0  
 ピン：リン青銅  
 PIN: PHOSPHOR BRONZE  
 ネール：リン青銅  
 NAIL: PHOSPHOR BRONZE

2. メッキ仕様

PLATING

PIN 接点部：パラジウムニッケル下地、金メッキ  
 CONTACT AREA: Au OVER Pd-NI  
 半田付け部：錫メッキ  
 SOLDER TAIL AREA: TIN  
 下地メッキ：ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL

NAIL 錫メッキ

TIN  
 下地メッキ：ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL

3. 推奨基板厚

RECOMMENDED P.C.B. THICKNESS:  $t \geq 0.8$  MIN.

4. 適合カード厚

RECOMMENDED CARD THICKNESS

接続部： $3.3 \pm 0.1$   
 CONNECTING AREA:  $3.3 \pm 0.1$

5. 適合カード幅

RECOMMENDED CARD WIDTH:  $42.8 \pm 0.1$

6. ハウジング色

HOUSING COLOR: WHITE

△1 寸 1, 13, 38, 50  
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS  
 1, 13, 38 AND 50.

△2 25, 26  
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.

△9 ピンの倒れは、ピン根元を基準に全方向へ  $0.1$  MAX. とする。  
 PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED  $0.1$   
 WHEN MEASURED FROM PIN BASE.

△10 ピン根元に適用する。  
 THIS DIMENSION TO BE MEASURED AT PIN BASE.

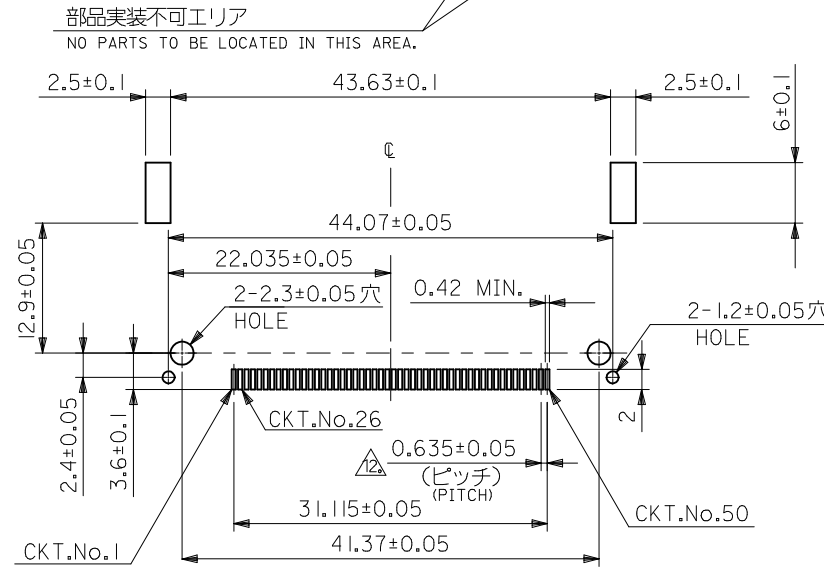
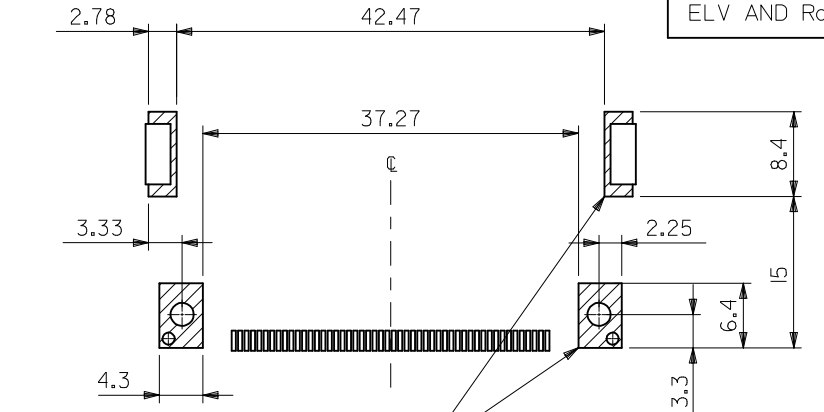
△11 ソルダーテールは、Z面を基準とし上へ  $0.05$  下へ  $0.2$  の範囲にあり、  
 目付ソルダーテールの平坦度は、 $0.15$  MAX. とし、テール先端にて測定する。  
 SOLDER TAILS TO BE WITHIN  $0.05$  UPWARD AND  $0.2$  DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF  
 SOLDER TAILS TO BE WITHIN  $0.15$ .  
 MEASUREMENT POINT IS SOLDER TAILS TIP.

△12 公差非累積  
 NON-CUMULATIVE

13. 本製品は 53927-\*\*-\*\*10 の鉛フリー一品である。  
 THIS PRODUCT IS LEAD FREE OF 53927-\*\*-\*\*10.

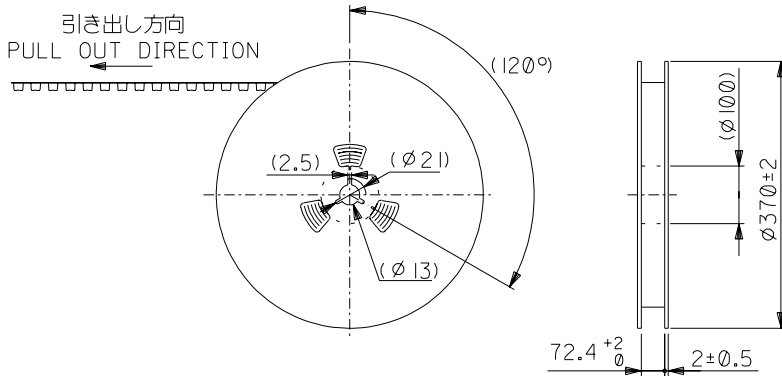
14. 実装時、ボルトとナットを使用すること。  
 USE THE BOLT AND THE NUT WHEN YOU MOUNT.

ELV AND RoHS COMPLIANT.



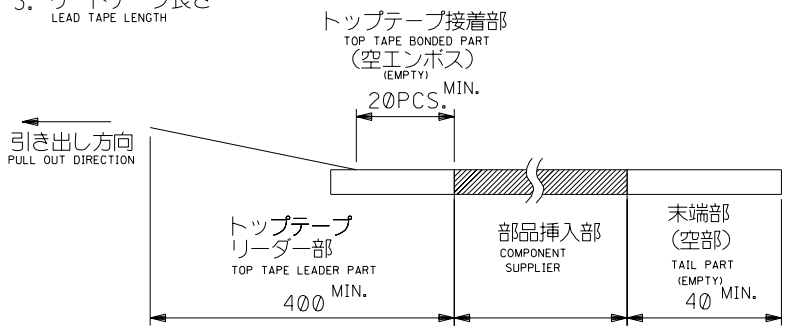
基板推奨寸法  
 RECOMMENDED P.C.B. LAYOUT

REVISED EC NO.: J2014-0889 2013/11/21 DRW: NESATO CHKD: ASHIMOTSU 2013/11/21 APPR: NUKITA 2013/11/21	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY T. UENO	DATE 2004/05/17	TITLE CFA CARD CONN. 50P HEADER ASSY -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/05/17					
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/05/17					
A	REV	ANGULAR	±3 °	MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-53927-001		SHEET NO. 2 OF 2		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



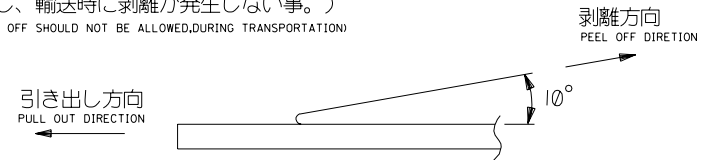
注)  
NOTES

- 製品番号 53927-5019 の詳細寸法については、SD-53927-001 を参照下さい。  
IN THE PACKAGE , PART NO. 53927-5019 DETAILED DIMENSIONS , SEE SD-53927-001
- 梱包数量 : 280 個/リール  
NUMBER OF CONNECTORS : 280 PCS/REEL
- リードテープ長さ  
LEAD TAPE LENGTH



- トップテープの剥離強度 : (剥離方向は下図参照)  
PEELING OFF FORCE OF TOP TAPE (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
0. 1~1. 3N {10~130gf} : キャリアテープ幅 72mm  
CARRIER TAPE WIDTH 72mm

尚、本規格値は、出荷時に適用。  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
(但し、輸送時に剥離が発生しない事。)  
(PEEL OFF SHOULD NOT BE ALLOWED DURING TRANSPORTATION)



- 材料  
MATERIAL  
キャリアテープ : ポリプロピレン (PP)  
CARRIER TAPE : POLYPROPYLENE (PP)  
トップテープ : PET, PE, PEF  
TOP TAPE : PET, PE, PEF  
リール : 紙  
REEL : CARD BOARD

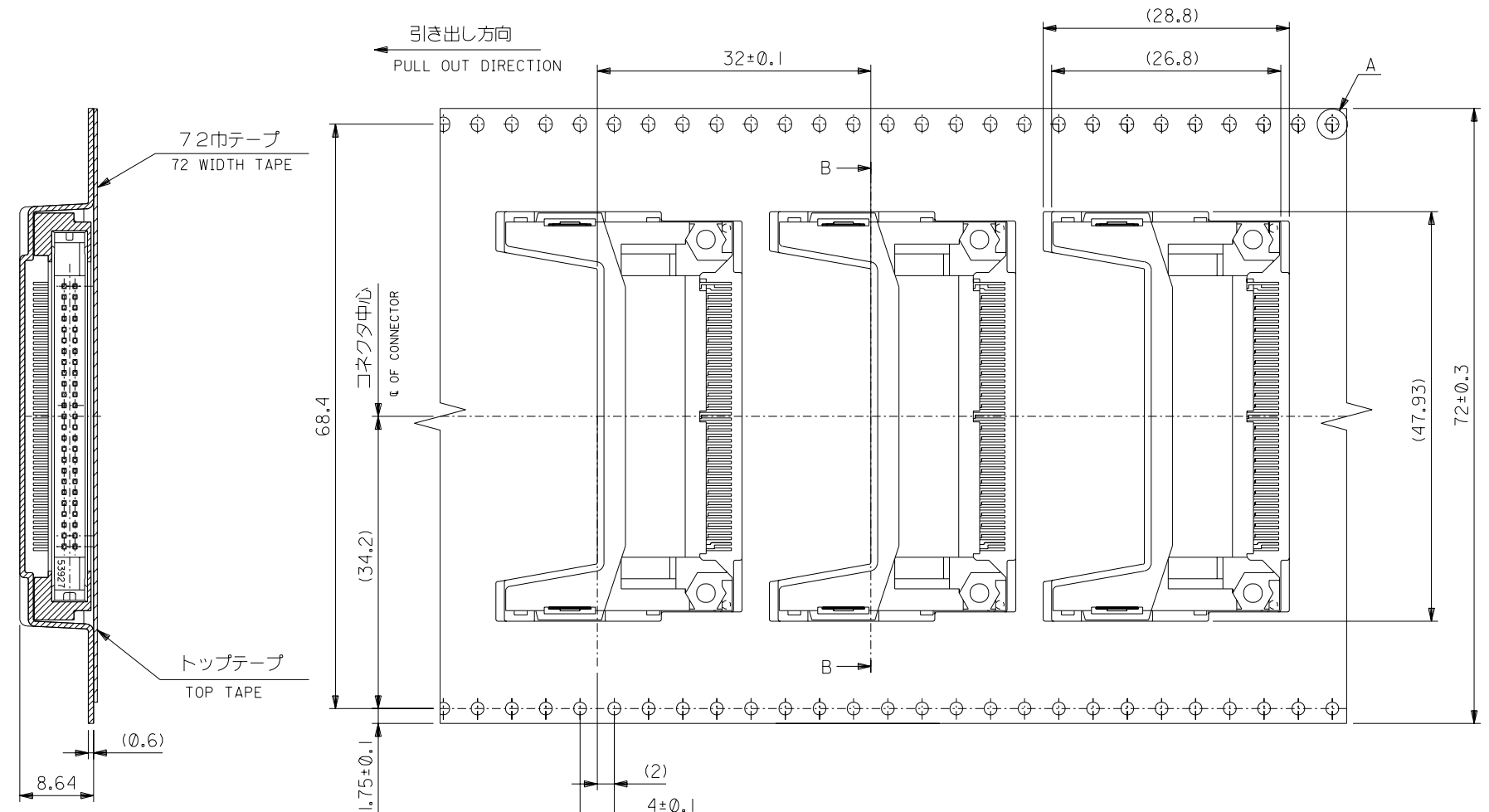
- 本製品は 53927- \*\* 18 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53927- \*\* 18.

53927- ** 78	53927-5078	50
MODEL NO.	MATERIAL NO.	種数 NO. OF CKTS.

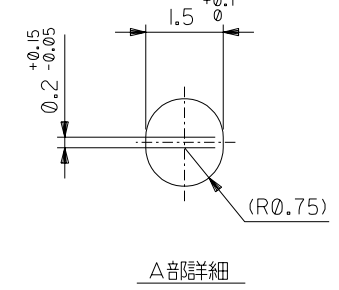
材料 MATERIAL		注参照 SEE NOTES		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH		---		REVISE ONLY ON CAD SYSTEM	
適用電線範囲 WIRE RANGE		---		TITLE 名称 53927-5019 TAPING PACKAGE -LEAD FREE-	
被覆外径 INS. RANGE		---		DRAWN BY 04/05/17 T.UENO	
DRAWN BY 04/05/17 T.UENO		CHK'D BY 04/05/17 M.SASAO		DWG. NO. (SHEET 1 OF 2)	
APP'D BY 04/05/17 M.SASAO		尺度 SCALE		REV 0	
記号 LTR		変更内容 REVISION RECORD		日付 DATE	
一般公差 GENERAL TOLERANCES		① 新規作成 RELEASED (J2004-426B)		M.S	

DWG. NO.  
SD-53927-002

ALL DIMENSIONS IN METRIC DO NOT SCALE DRAWING



断面 B - B  
SECTION B-B



累積ピッチ : 40±0.2  
ACCUMULATIVE  
PITCH : 40±0.2

角度 ANGLE	+30					材料 MATERIAL	注参照 SEE NOTES	MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
30 以上 OVER	+0.3					仕上げ FINISH	—	
10 以上 30 未満 OVER 30 UNDER	+0.25					適用電線範囲 WIRE RANGE	—	TITLE 名称
10 未満 UNDER	+0.2					被覆外径 INS. RANGE	—	53927-5019
一般公差 GENERAL TOLERANCES		SEE SHEET 1 OF 2				DRAWN BY 04/05/17 T.UENO	CHK'D BY 04/05/17 M.SASAO	TAPING PACKAGE
記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE	APP'D BY 04/05/17 M.SASAO	尺度 SCALE	2 - 1		-LEAD FREE-
								DWG. NO. (SHEET 2 OF 2)
								SD-53927-002
								REV 0